

## Excellent Integrated System Limited

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[Samsung Electro-Mechanics America, Inc.](#)  
[CL31B123JBCNNC](#)

For any questions, you can email us directly:

[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)



## SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL31B123JBCNNNC**
- Description : **CAP, 12nF, 50V, ±5%, X7R, 1206**

### A. Samsung Part Number

CL  
 31  
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 123  
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 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L: 3.2 ± 0.15 mm	W: 1.6 ± 0.15 mm
③ Dielectric	X7R	⑧ Inner electrode	Ni
④ Capacitance	12 nF	Termination	Cu
⑤ Capacitance tolerance	± 5 %	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	50 V	⑨ Product	Normal
⑦ Thickness	0.85 ± 0.15 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Cardboard Type, 7" reel

### B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz±10%      1.0±0.2Vrms
Tan δ (DF)	0.025 max.	
Insulation Resistance	10,000Mohm or 500Mohm·μF Whichever is Smaller	Rated Voltage      60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	X7R (From -55°C to 125°C, Capacitance change should be within ±15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10±1 sec.
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	1) Sn63Pb37 solder 235±5°C, 5±0.5sec. 2) SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±7.5% Tan δ, IR : initial spec.	Solder pot : 270±5°C, 10±1sec.

	Performance	Test condition
<b>Vibration Test</b>	Capacitance change : within $\pm 5\%$ Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Humidity</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.05 max IR : 1000Mohm or 50Mohm $\cdot \mu F$ Whichever is Smaller	40 $\pm 2$ °C, 90~95%RH, 500+12/-0hrs
<b>Moisture Resistance</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.05 max IR : 500Mohm or 25Mohm $\cdot \mu F$ Whichever is Smaller	With rated voltage 40 $\pm 2$ °C, 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 12.5\%$ Tan $\delta$ : 0.05 max IR : 1000Mohm or 50Mohm $\cdot \mu F$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 7.5\%$ Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperatur $\rightarrow$ 25°C $\rightarrow$ Max. operating temperature $\rightarrow$ 25°C  5 cycle test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.